Product Change Notification: CAAN-10FNAM315

Date:

13-Feb-2026

Product Category:

Memory

Notification Subject:

CCB 7573.002 and CCB 7573.003 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for AT93C86A-10SU-1.8, AT93C86A-10SU-1.8-T, AT93C86A-10SU-2.7 and AT93C86A-10SU-2.7-T catalog part numbers (CPN) available in 8L SOIC (.150in) package assembled at ANAP and ASSH sites.

Affected CPNs:

CAAN-10FNAM315_Affected_CPN_02132026.pdf
CAAN-10FNAM315_Affected_CPN_02132026.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for AT93C86A-10SU-1.8, AT93C86A-10SU-1.8-T, AT93C86A-10SU-2.7 and AT93C86A-10SU-2.7-T catalog part numbers (CPN) available in 8L SOIC (.150in) package assembled at ANAP and ASSH sites.

Pre and Post Summary Changes:

	Pre Change		**Post Change**		**Change** (Yes/No)
Assembly Site	Amkor Technology Philippine	ATX Semiconductor (Shanghai) Co.	Amkor Technology Philippine	ATX Semiconductor (Shanghai) Co.	No

	(P1/P2), Inc. (ANAP)	Ltd (ASSH)	(P1/P2), Inc. (ANAP)	Ltd (ASSH)	
Wire Material	Au		CuPdAu		Yes
Die Attach Material	8290 (PFAS)	EN-4900G (PFAS-free)	AMK-EP27 (PFAS-free)	EN-4900G (PFAS-free)	Yes (for ANAP site)
Molding Compound Material	G600	CEL-9240HF10AK	AMK-MC27	CEL-9240HF10AK	Yes (for ANAP site)
Lead-Frame Material	C194	C194	C194	C194	No
Lead-Frame Paddle Size	90 x 90 mils	93 x 93 mils	60 x 60 mils	93 x 93 mils	Yes (for ANAP site)
DAP Surface Prep	Ag	Bare Cu	Bare Cu	Bare Cu	Yes (for ANAP site)
Lead-Frame Design	See Pre and Post Change for Comparison (for ANAP site)				

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material.

Change Implementation Status: In Progress

Estimated First Ship Date: 30 April 2026 (date code: 2618)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	February 2026				>	April 2026				
Work Week	06	07	08	09		14	15	16	17	18
Qual Report Availability		X								
Final PCN Issue Date		X								
Estimated Implementation Date										X

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: February 13, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_CAAN-10FNAM315_Pre and Post Change Summary_ANAP.pdf
PFAS Elimination and Die Attach_Explanation.pdf
PCN_CAAN-10FNAM315_Qual_Report_ASSH.pdf
PCN_CAAN-10FNAM315_Qual_Report_ANAP.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.